

SOT644-1

plastic low profile fine-pitch ball grid array package; 144 balls; body 12 x 12 x 0.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFPGA144
Package type industry code	LFPGA144
Package style descriptive code	LFPGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	5-2-2003

Table 1. Package summary

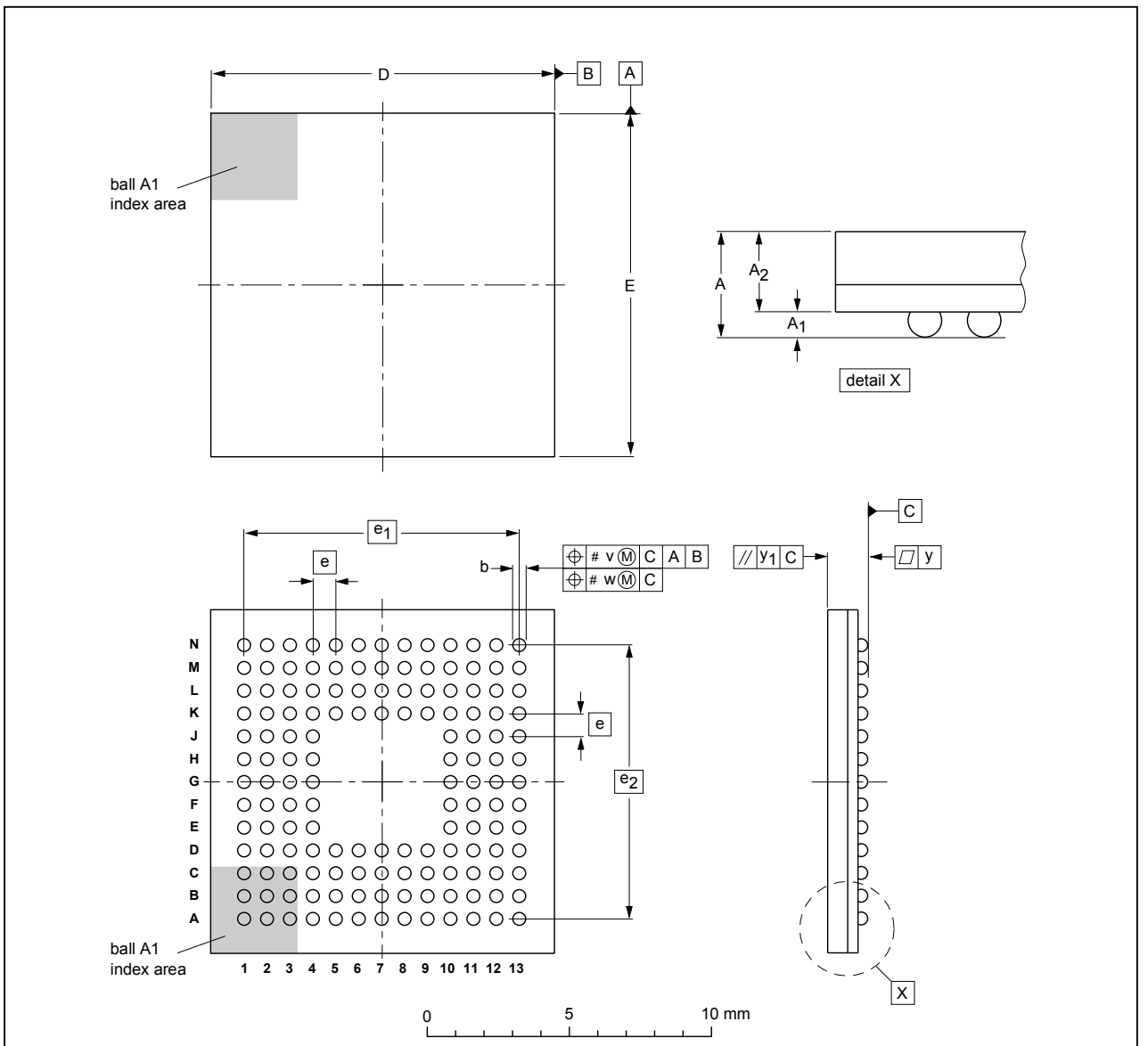
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	[tbd]	-	1.35	1.35	mm
A ₂	package height	0.82	-	0.9	1	mm
n ₂	actual quantity of termination	-	-	144	-	



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2. Package outline

LFBGA144: plastic low profile fine-pitch ball grid array package; 144 balls; body 12 x 12 x 0.9 mm SOT644-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1.35	0.41 0.31	1.00 0.82	0.51 0.41	12.1 11.9	12.1 11.9	0.8	9.6	9.6	0.15	0.1	0.1	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT644-1		MO-205				-00-10-16- 03-02-05

Fig. 1. Package outline LFBGA144 (SOT644-1)

3. Soldering

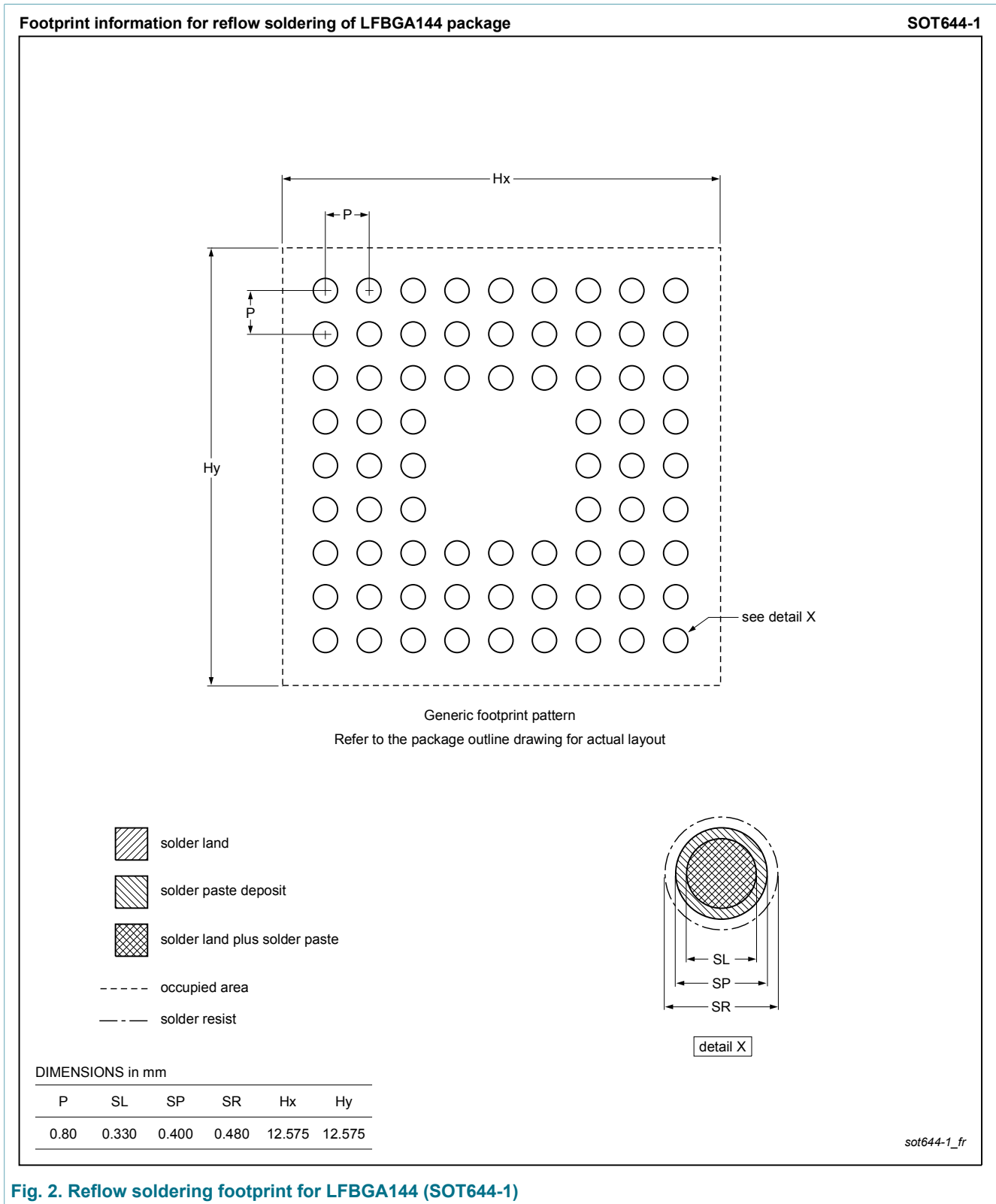


Fig. 2. Reflow soldering footprint for LFBGA144 (SOT644-1)

4. Legal information

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For sales office addresses, please send an email to: salesaddresses@nxp.com
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